



#6 file
Docket No.: M1071.1453/P1453
1/29/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Haruhiko Ikeda

Application No.: 09/927,053

Group Art Unit: 1733

Filed: August 9, 2001

Examiner: Not Yet Assigned

For: METHOD OF BONDING A
CONDUCTIVE ADHESIVE AND AN
ELECTRODE, AND A BONDED
ELECTRODE OBTAINED THEREBY

CHANGE OF CORRESPONDENCE ADDRESS

Commissioner for Patents
Washington, DC 20231

Dear Sir:

In accordance with the Manual of Patent Examining Procedures, Section 601.03, please change the mailing address for all correspondence in the above-identified patent application to:

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Dated: January 14, 2003

Respectfully submitted,

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